

LS-3700

- In-tray scanning - no part handling
- Demonstrated up time of 99%+
- Over 350 device & tray combinations programmed for production
- Less than 30 second software changeover time
- Proven to inspect ultra fine pitch (0.3 mm)
- High throughput: up to 6500 UPH for TSOP's - up to 5000 UPH for QFP's

The LS-3700 is a 3-D machine vision-based component inspection system. The system inspects a variety of leaded and grid array components, without physical contact, while seated in their trays. The software includes modules that gather high resolution 3-dimensional data from the surface of the leads, make geometric measurements and determine if components are within specified limits. Scanning of Intel Flash components in PSOP, SSOP, TSOP and other surface mount packages are all available on RVSI lead scanning products. The system software is divided into four major sections:

1. Data Acquisition. This software does the scanning and surface mapping of the leads.

2. Segmentation and Measurement. This section does the basic geometric measurements of each lead and allows the analysis section to evaluate the condition of the component. More importantly, this output can be used to generate variable data that support "x" bar and "r" charts for most process indicators.

3. Analysis. This section uses previously generated measurements to determine the various characteristics of the component, including SPC charts and lot histograms.

4. User interface. The system interfaces with the operator via user-friendly menus. During normal inspection, the software automatically makes all the necessary



internal adjustments. It self-calibrates so that the operator typically only has to load the trays and press "Go" without further action.

The LS-3700 system includes inspection software to detect and classify a variety of measurements and reports defects when they are outside specified limits. These parameters include: coplanarity, pin spread at tip (pitch), pin width at tip, gap width at tip, footprint, standoff, total package height, lead angle, terminal dimension and tip burr (optional).

Besides calling out defects, the LS-3700 system can provide dimensional measurements of the leads, such as foot angle and lead spread. This accurately and consistently measured geometric data is especially suitable as a real time feedback for statistical process control. These capabilities are provided as an enhancement through the network services option.

INTEL FLASH MEMORY SUPPORTED:

28F010, 28F001BX, 28F020, 28F002BC, 28F002BL, 28F002BV, 28F002BX, 28F200BL, 28F200BV, 28F200BX, 28F200CV, 28F004BE, 28F004BL, 28F004BV, 28F004BX, 28F004SC, 28F400BL, 28F400BV, 28F400BX, 28F400CE, 28F400CV, 28F008BE, 28F008BV, 28F008SA, 28F008SC, 28F800BV, 28F800CE, 28F800CV, 28F016SA, 28F016SC, 28F016SV, 28F016XD, 28F016XS, 28F032SA

AVAILABILITY:
Now

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RVSI